



Welcome to this edition of the SIE Computing Solutions newsletter, designed to keep you, our partners and customers, in the know with recent developments in and around our company and its products. We hope this provides a helpful resource for this month, and we encourage you to contact us with any questions, suggestions, or proposals via our online form or by sending an email to pr@sie-cs.com.

PRODUCT SPOTLIGHT

3U 5-Slot VPX Portable Enclosure

The newest addition to SIE's 585 Series, the 3U VPX portable lightweight aluminum enclosure is designed for use in VPX product development and testing. The air-cooled open design and 5-slot full mesh backplane enable efficient software component and card testing within a full system at a lower cost than traditional VPX enclosures.

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WHAT'S NEW

SIE Welcomes New Regional Managers

SIE is pleased to announce the appointment of two new regional sales managers, Tim Bellamy and SIE veteran Steve Corbesero.

Western Regional Sales Manager Tim Bellamy has worked in the embedded technology and connector industry as a product manager, business development manager, and national sales manager before taking over responsibility for SIE's western U.S. sales efforts, including management of multiple manufacturers' representative organizations in the region.

Southeast Area Business Development Manager Steve Corbesero joined SIE in 1991 as an engineering manager and held engineering positions at Augat and Raytheon before making the switch to sales. He will be responsible for expanding sales in SIE's southeast territory.

SIE Talks OpenVPX with Industry Experts

Check out *Military & Aerospace Electronics'* most recent webinar on OpenVPX 1.0 in military systems featuring SIE's Ian Day, along with senior scientists and engineers from Boeing, Curtiss Wright, and GE Intelligent Platforms.

[Open Webinar >](#)

NEWS

SIE Introduces New ATR Thermal Load Card

SIE's new ATR thermal load card is designed for testing thermal dynamics in a conduction-cooled environment. The 3U x 160 mm card is configurable by power loads ranging from 12, 25, 50 and up to 200 watts to accommodate any of the common bus structures used in ATRs such as VPX, VME and CompactPCI. The new SIE ATR card enables users to perform thermal profiling of an ATR enclosure in order to obtain empirical data on the system's thermal load, enabling each slot in the system to be maximized. This alleviates the need to perform testing with production-grade cards, which can reduce costs by a factor of 10 or more. Each slot can also host a thermal load card to mirror the final system configuration in order to create an integrated system thermal profile.

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SIE Wraps Up Successful Year in 2009

Strengthening its electronic packaging industry leadership last year, SIE's growth was marked by several major milestones after its April 2009 acquisition by global embedded computing company S.I.E. AG. New product development was highlighted by the innovative [720 Series Liquid Cooled ATR](#), the latest addition to the ATR 700 Series that meets the cooling requirements of high thermal load systems (like those based on VPX) that can not be satisfied by convection and conduction cooling alone. An agreement with England's ACAL Microsystems to act as the company's exclusive UK sales partner and the hiring of industry veteran Ian Day also helped to continue to widen company reach beyond the U.S.

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SIE's VPX Backplane Wins VME & Critical Systems Editors Choice Product Award

SIE's [5-slot I/O PLUS 3U VPX Full Mesh Backplane](#) was named an [Editor's Choice Product Award](#) winner by leading industry publication *VME & Critical Systems* in its final issue of 2009. Designed for a wide array of VPX applications, the backplane's I/O PLUS provides greater flexibility through the use of interchangeable daughter cards to reduce the need for custom backplanes for each application.

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UPCOMING EVENTS

- [General Police Equipment Exhibition and Conference](#)
Leipzig, Germany
May 4-6, 2010
- [AFCEA Symposium](#)
Bonn, Germany
May 5-6, 2010
- [RTECC Boston](#)
Boston, MA, USA
May 25, 2010